501770588 12/28/2011

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|---------------|----------------|
| Jeong Hun LEE | 12/20/2011 |

RECEIVING PARTY DATA

| Name: | Hynix Semiconductor Inc. | |
|-----------------|------------------------------|--|
| Street Address: | San 136-1, Ami-ri, Bubal-eub | |
| City: | Icheon-si, Gyeonggi-do | |
| State/Country: | REPUBLIC OF KOREA | |

PROPERTY NUMBERS Total: 1

| Property Type | Number | |
|---------------------|----------|--|
| Application Number: | 13339050 | |

CORRESPONDENCE DATA

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| ATTORNEY DOCKET NUMBER: | PA0510-0 |
|-------------------------|-----------------------|
| NAME OF SURMITTER | Woochoon William Park |

Total Attachments: 2

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PATENT REEL: 027454 FRAME: 0145 OF \$40.00 15558050

ASSIGNMENT OF APPLICATION

Now, therefore, in consideration of the sum of one dollar (\$1), the receipt whereof is acknowledge, and other good and valuable consideration, I/We, the assignor(s)

ASSIGNOR(S)

Jeong Hun LEE #209-504, Jugong Apt., 202 Panam-dong, Dong-gu, Daejeon, Republic of Korea

by these presents do sell, assign and transfer unto said assignee

ASSINGEE

Hynix Semiconductor Inc. San 136-1, Ami-ri, Bubal-eub, Icheon-si, Gyeonggi-do, Republic of Korea

and the heirs, successors, assigns and legal representatives of the assignee the full and exclusive right to the said invention in the United States which are disclosed in the U.S. patent application titled

SEMICONDUCTOR SYSTEM INCLUDING SEMICONDUCTOR DEVICE

| ☐ for which an application for a Number | united States Patent was filed c _; or | on Application |
|--|---|---|
| ☐ for which an application for a | United States Patent was execu | uted by the undersigned on |
| Patents which may be granted the Director of the U.S. Patent assignee, of the entire right, title of his legal representatives, to | therefore in the United States. In and Trademark Office to issue s e, and interest in and to the same the full end of the term for which | and interest in and to any and all We hereby authorize and request said United States Patent to said e, for his sole use and for the use in said Patent may be granted, as and this assignment and sale no |

The assignor(s) agree promptly upon request of the Assignee, its heirs, successors, assigns and legal representatives of the assignee to communicate any facts known to it respecting the patent and the invention set forth therein, and to execute and deliver without further compensation any power of attorney, Assignment, application, whether original, continuation, divisional or reissue, or other papers that may be necessary.

Assignor(s) hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

Assignor(s) further covenants that assignee will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to Assignor(s) and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to assignee or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

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REEL: 027454 FRAME: 0146

DOCKET:

PATENT

ASSIGNOR SIGNATURE(S)

Jeong Hun LEE

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RECORDED: 12/28/2011

REEL: 027454 FRAME: 0147